

国家重点研发计划“高能环形正负电子对撞机关键技术研发和验证”项目结题自
评价会议 MOST CEPC Project Final assessment Meeting

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Sensor chip design and testing 传感器芯片设计与测试
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Presenter: ZHANG, Ying (IHEP)

Session Classification: Task2 课题二: 硅径迹探测器关键技术验证